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Substitute for form 1449A/PTO		Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>		Application Number	10/758,822
		Filing Date	11/16/2004
		First Named Inventor	VAHID GOUDARZI
		Group Art Unit	2841
		Examiner Name	HOA C. NGUYEN
Sheet	1	of	
		Attorney Docket No.	CE1151&JGN

U. S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

Examiner Signature	H. G. Gandy	Date Considered	8/29/2005
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation, if not in conformance and not considered. Include copy of this form with next communication to applicant.

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Substitute for form 1449A/PTO		<i>Complete if Known</i>	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Application Number	10/758,822
		Filing Date	11/12/04
		First Named Inventor	VAHID GOUDARZI
		Group Art Unit	28-01
		Examiner Name	HOA C. NGUYEN
Sheet	1	of	Attorney Docket No.
			CE11518JGN

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹
HN		"lead-Free Mandate Plumbs New Design Challenges" - Schweber, Bill; www.ednmag.com , 4/18/2002	
HN		"Fujitsu Develops Advanced Printing Bump Technology" - Fujitsu Laboratories; http://pr.fujitsu.com/en/news/2001/12/12-1.html , 12/12/2001	
HN		"A Constitutive Model for Creep of Lead-Free Solders Undergoing Strain-Enhanced Microstructural Coarsening: A First Report" - Dutta, I; Journal of Electronic Materials, 2002	

Examiner Signature	<i>Hoang Nguyen</i>	Date Considered	8/29/05
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